

What is claimed is:

1. In a weld-solder filler composition utilized in soldering and welding processes, the improvement comprising said weld-solder filler composition containing, in percent by weight:

0.5 to 7.0% Al;

0.5 to 2.0% Mn;

0.01 to 4% Fe;

0.01 to 6% Ni;

no more than 1.0% impurities; and
the remainder being Cu.

2. The weld-solder filler composition of Claim 1, wherein the following impurities, if present, are contained in the indicated ranges:

0.01 to 0.3% Si;

0.01 to 1.0% Zn;

0.01 to 0.5% Sn;

0.01 to 0.1% Cr; and

0.01 to 0.1% Co.

3. The weld-solder filler composition of Claim 1, wherein 6% Al, 1% Mn and 1% Ni are present in the filler composition.

4. The weld-solder filler composition of Claim 1, wherein 5% Al, 1% Mn and 1% Ni are present in the filler composition.

5. The weld-solder filler composition of Claim 1, wherein 5% Al is present in the filler composition.